PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT7105269

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SHIANG-CHI LIN	09/23/2021
HRISHIKESH VIJAYKUMAR PANCHAWAGH	01/03/2022
JESSICA LIU STROHMANN	09/12/2021
YIPENG LU	09/19/2021
CHIN-JEN TSENG	09/13/2021
KOSTADIN DIMITROV DJORDJEV	09/13/2021
MIN-LUN YANG	09/14/2021
CHIA-WEI YANG	09/13/2021

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17446436

CORRESPONDENCE DATA

Fax Number: (510)663-0920

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 5106631100
Email: jmorrison@wavsip.com
Correspondent Name: WEAVER AUSTIN VILLENEUVE & SAMPSON LLP
Address Line 1: P.O. BOX 70250
Address Line 4: OAKLAND, CALIFORNIA 94612-0250

ATTORNEY DOCKET NUMBER:	QUALP554US
NAME OF SUBMITTER:	ROGER S. SAMPSON
SIGNATURE:	/Roger S. Sampson/

DATE SIGNED:	01/05/2022

Total Attachments: 10
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ASSIGNMENT

WHEREAS, WE,

1. **Shiang-Chi LIN,** having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.,**
2. **Hrishikesh Vijaykumar PANCHAWAGH,** having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.,**
3. **Jessica Liu STROHMANN,** having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.,**
4. **Yipeng LU,** having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S. A.,**
5. **Chin-Jen TSENG,** having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.,**
6. **Kostadin Dimitrov DJORDJEV,** having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.,**
7. **Min-Lun YANG,** having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.,**
8. **Chia-Wei YANG,** having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.,**

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **UNDER-DISPLAY ULTRASONIC FINGERPRINT SENSORS FOR FOLDABLE DISPLAYS** (collectively the **"INVENTIONS"**) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter **"ASSIGNEE"**), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to **U.S. Application No(s). 17/446,436** filed **August 30, 2021, Qualcomm Reference Number 2104527**, and all provisional applications relating thereto (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number (s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States or in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to me respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Hsinchu, Taiwan, on Sep. 23rd 2021 Shiang-Chi Lin

City, State, Country Date Shiang-Chi LIN

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Cupertino, CA, USA on 01/03/2022 H.V. Panchawagh

City, State, Country — Date — Hrishikesh Vijaykumar PANCHAWAGH

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Cupertino, CA, USA on 9/12/2021

City, State, Country
Date
Jessica Liu STROHMANN

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at	Davis, CS, USA,	on	09/19/2021	
	City, State, Country		Date	Yipeng LU

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Santa clara, CA, USA on 9/13/2021 Chinjen Tseng

City, State, Country | Date | Chin-Jen TSENG

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Los Gatos, CA, on 09/13/2021

City, State, Country — Date — Kostadin Dimitrov DJORDJEV

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Hsinchu, Taiwan, on 9/14 2021 Min-Lun Yang

City, State, Country Date Min-Lun YANG

Qualcomm Reference Number: 2104527
Document ID: 1631190319802 v1

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Hsinchu, Taiwan on 9/13 2021 Chia Wei Yang
City, State, Country Date Chia-Wei YANG